

Description

METHOD OF FORMING FET SILICIDE GATE STRUCTURES INCORPORATING INNER SPACERS

BACKGROUND OF INVENTION

[0001] This application is related to Application FIS9-2003-0124, "FET gate structure with metal gate electrode and silicide contact," filed the same day and assigned to the same assignee as the present application. The disclosure of the above-noted application is incorporated herein by reference.

[0002] This invention relates to the manufacture of advanced semiconductor devices, particularly advanced CMOS integrated devices in which metal gate electrodes are used.

[0003] With the continued scaling of CMOS devices to smaller dimensions, the gate dielectrics of these devices have been reduced to thicknesses well below 20Å . This in turn has led to greatly increased gate leakage currents and diffusion of dopants from the polysilicon gate structures (often

referred to as the poly depletion effect).

[0004] Alternatives to doped polysilicon, such as metals and silicides, are now being used in gate structures to mitigate the poly depletion effect and control the leakage current, and thus to ensure electrical performance in highly integrated CMOS devices. A silicide gate is typically formed by a "salicide" process, in which a polysilicon gate having n+ and p+ areas is covered with a layer of silicide-forming metal (e.g. Co) and then converted to a metal silicide.

[0005] Figures 1A–1C are schematic illustrations of a typical polysilicon gate structure. Figure 1A is a plan view of structure 10, which includes n+ polysilicon gate 11 and p+ polysilicon gate 12. As shown in Figure 1A, the n+ and p+ regions are in contact; this structure is typically found in SRAM devices. The top surface of the gate structure is generally covered with a hardmask (typically nitride) 17. A nitride etch stop layer 13 and HDP oxide 14 have been deposited over the gate regions. (Oxide region 14 is preferably HDP oxide rather than BPSG, in order to permit processing at lower temperatures.) Figure 1B is a longitudinal cross-section view, showing that the gate regions 11, 12 are formed on a gate oxide layer 15 overlying substrate 1. Figure 1C is a transverse cross-section view,

showing nitride spacers 16, the nitride etch stop layer 13 and HDP oxide 14 on either side of the polysilicon gate. Conversion of the gate structure to a silicide involves removing the etch stop 13 and hardmask 17 from the top of the gate, then depositing a layer 18 of silicide-forming metal on the polysilicon (see Figure 2A). A salicide process is then performed (details of which are known in the art) to convert the respective polysilicon regions 11, 12 to a silicide layer having regions 19a, 19b (Figure 2B).

[0006] The difference in doping between polysilicon regions 11 and 12 leads to formation of silicide regions of different composition; for example, Co_xSi_y in region 19a, Co_wSi_z in region 19b. This in turn leads to formation of a high-resistivity region near the interface between regions 19a and 19b. In addition, it is desirable to provide different stresses for gate regions 19a and 19b (which will become NFET and PFET gates respectively). Accordingly, there is a need for a silicide-gate process in which the polysilicon gate regions are separately converted to a silicide, as opposed to conversion simultaneously using a blanket metal layer.

SUMMARY OF INVENTION

[0007] The present invention addresses the above-described

need by providing a method for fabricating a gate structure for a semiconductor device in which the gate structure has an inner spacer. According to a first aspect of the invention, this is done by first removing material in a gate region of the device to expose a portion of the substrate, forming a gate dielectric on the exposed portion of the substrate, and then forming an inner spacer layer overlying the gate dielectric and the dielectric material. A silicon layer is then formed which overlies the inner spacer layer. The structure is then planarized (that is, a first portion of the silicon layer and a first portion of the inner spacer layer are removed), so that the top surface of adjacent dielectric material is exposed while a second portion of the silicon layer and a second portion of the inner spacer layer remain in the gate region and have surfaces coplanar with the top surface. A silicide gate structure is then formed from the second portion of the silicon layer; the silicide gate structure is separated from the dielectric material by the second portion of the inner spacer layer.

[0008] The semiconductor device may include a first gate region and a second gate region with an interface therebetween, with the inner spacer layer covering the interface. When the device has two gate regions, the above-described

process may be used in both gate regions, so as to produce separate silicide structures, with an inner spacer separating the two structures.

[0009] According to a second aspect of the invention, a gate structure (adjacent to a dielectric material) is fabricated by removing material in a gate region to expose a portion of the substrate; forming a temporary gate dielectric on that exposed portion; and forming an inner spacer layer overlying the gate dielectric and the dielectric material. The temporary gate dielectric and a first portion of the inner spacer layer are removed, so that the top surface of the dielectric material is exposed and a portion of the substrate is again exposed. A new gate dielectric is formed on that exposed portion of the substrate; a silicon layer is then formed overlying the inner spacer layer and overlying the top surface of the dielectric material. The structure is then planarized (that is, a first portion of the silicon layer is removed), so that the top surface of the dielectric material is exposed and a second portion of the silicon layer remains in the gate region and has a surface coplanar with the top surface; a silicide gate structure is then formed from the second portion of the silicon layer.

[0010] The semiconductor device is typically fabricated on a

wafer; the inner spacer layer and silicon layer are respectively formed by depositing a blanket nitride layer and a blanket silicon layer on the wafer.

[0011] According to another aspect of the invention, a semiconductor device having a gate structure on a substrate is provided. This gate structure is adjacent to a dielectric material having a top surface, and includes a gate dielectric overlying a portion of the substrate in a gate region and in contact therewith. The structure also includes an inner spacer layer in contact with the dielectric material, and a silicide structure having an upper surface coplanar with the top surface. The gate region may be viewed as a trench having a bottom and sidewalls, with the gate dielectric overlying the bottom of the trench, the inner spacer layer in contact with the sidewalls of the trench, and the silicide structure filling the trench. In particular, the gate region may have a first silicide structure and a second silicide structure, with a portion of the inner spacer layer separating the first silicide structure and the second silicide structure.

BRIEF DESCRIPTION OF DRAWINGS

[0012] Figure 1A is a schematic illustration in plan view of a typical CMOS gate structure with n+ and p+ polysilicon re-

gions.

- [0013] Figure 1B is a longitudinal cross-section view of the gate regions of Figure 1A.
- [0014] Figure 1C is a transverse cross-section view of the gate regions of Figure 1A.
- [0015] Figures 2A and 2B are schematic longitudinal cross-section views of a typical process whereby n+ and p+ polysilicon gate regions are converted to silicide.
- [0016] Figures 3-8 illustrate steps in a process for forming a silicide gate structure in one gate region using inner spacers, in accordance with a first embodiment of the invention.
- [0017] Figures 9A-9H illustrate steps in a process for forming a silicide gate structure in another gate region, using the process of Figures 3-8.
- [0018] Figures 10-12 illustrate steps in a process for forming a silicide gate structure in a gate region using inner spacers, in accordance with a second embodiment of the invention.

DETAILED DESCRIPTION

- [0019] The embodiments of the invention will be described as part of a replacement-gate process, in which a polysilicon gate stack is built on a substrate and removed after source and drain regions are formed. The typical gate

structure of Figures 1A–1C, having n+ polysilicon gate 11 and p+ polysilicon gate 12, is the starting point for the embodiments of the invention described herein.

[0020] First Embodiment: Blanket nitride layer for inner spacer

[0021] In this embodiment, an inner spacer, typically of silicon nitride, is formed in the trench created by removal of the polysilicon gate; this inner spacer permits separate formation of silicide gates in different regions. Figure 3 is a transverse cross-section view of the structure at the beginning of the process, showing the nitride etch stop 13 and HDP oxide 14 overlying hardmask 17 and gate region 12, with nitride spacers 16 on either side of the polysilicon gate. As shown in Figure 3, the structure has been planarized after the nitride and oxide deposition processes. The entire structure (both n+ and p+ regions) is further planarized to expose the hardmask 17 (see Figure 4).

[0022] At this point the hardmask covering the n+ gate region 11 (not shown) is covered with photoresist 50, so that the only exposed hardmask is that covering region 12. The exposed hardmask 17 is removed, and then the underlying p+ polysilicon gate 12 and gate oxide 15 are also removed (see Figure 5). A trench 55 is thus formed, with an

exposed portion of the substrate 1 at the bottom of the trench.

[0023] After photoresist 50 is removed, a new gate dielectric 61 is formed on the exposed substrate at the bottom of trench 55. The gate dielectric may be a thermal oxide, or alternatively a high- k material deposited by molecular-organic chemical vapor deposition (MOCVD) or by atomic layer deposition (ALD). A blanket layer 62 of nitride is then deposited, covering the sidewalls of the trench and the gate dielectric (see Figure 6). At this point it should be noted that nitride layer 62 covers all sidewalls of trench 55, including the sidewall at the interface between gate region 12 and gate region 11. This is in contrast to previously formed spacers 16, which extend only in the longitudinal direction and thus cannot separate the respective gate regions from each other.

[0024] A blanket layer 71 of polysilicon is then deposited to cover nitride layer 62 and fill trench 55 (see Figure 7). A planarization process is performed, preferably chemical-mechanical polishing (CMP), to remove the polysilicon and nitride from the top surface of the HDP oxide, leaving a polysilicon gate 72 with a nitride inner spacer 63 in the trench (see Figure 8). The polysilicon gate 72 is then con-

verted to a silicide, using processes which are known in the art (including annealing and wet etching after the silicide is formed). At this point it should be emphasized that the other polysilicon gate region (n+ region 11 in this embodiment) is not affected by the above-described gate-replacement and silicidation processes, since that region remains covered by a portion of the original hardmask 17.

[0025] The process of this embodiment continues with the replacement and silicidation of the n+ polysilicon gate region 11, as shown in Figures 9A–9H. Figure 9A is a longitudinal cross-section (compare Figure 1B) of the structure after the silicidation process in the p+ polysilicon gate region. Figure 9A may be understood as an alternate view of the structure shown in Figure 8. As shown in Figure 9A, inner spacer 63 covers the sidewalls of the trench occupied by silicide gate structure 73, and in particular covers the boundary with n+ polysilicon region 11. The remaining portion of hardmask 17 is removed (Figure 9B). The polysilicon gate and underlying gate oxide 15 are removed, forming a trench analogous to trench 55 discussed above, exposing a portion of substrate 1 in the gate region and exposing inner spacer 63 at the interface

between regions (Figure 9C).

- [0026] A new gate dielectric 91 is formed on the exposed portion of the substrate. As noted above, this gate dielectric may be a thermal oxide, or alternatively a high- k material deposited by MOCVD or by ALD. A blanket layer 92 of nitride is then deposited, covering the sidewalls of the trench and gate dielectric 91, and also covering silicide structure 73 (see Figure 9D). A blanket layer 95 of polysilicon is deposited to fill the trench (Figure 9E); layer 95 is separated from silicide structure 73 by nitride layer 92. The structure is then planarized so that polysilicon outside the trench is removed. The remaining polysilicon is converted to a silicide 98 (Figure 9F). Finally, nitride layer 92 is etched so that the nitride layer forms an inner spacer 93 while silicide structure 73 is again exposed (Figure 9G). It is noteworthy that the materials and processes used in building the silicide structures in the two regions are independent. Accordingly, silicide 73 (in the region formerly p+ gate 12) and silicide 98 (in the region formerly n+ gate 11) may have different compositions and properties, to better meet device design/performance requirements.
- [0027] A metal layer 99 may then be deposited on both silicide structures 73, 93, in order to make electrical contact to

both regions (Figure 9H).

[0028] As shown in Figures 9G and 9H, in this embodiment two inner spacers 63, 93 separate the silicide structures 73, 98 at the interface between them. A comparison with Figure 1B shows that the previous n+ and p+ polysilicon gate regions have been converted into silicide gate regions each having an inner spacer, with the inner spacers in contact at the boundary between the gate regions. With regard to separating the different silicide structures, it will be appreciated that formation of the second inner spacer 93 is optional; the interface may be covered by inner spacer 63 alone.

[0029] Second Embodiment: Etched nitride layer

[0030] In this embodiment, the blanket nitride layer 62 is etched so that only the sidewalls of the trench are covered by the inner spacer. The gate structure is processed as described in the first embodiment, to the point shown in Figure 6 (that is, a blanket nitride layer 62 covers the sidewalls and bottom of the trench). Layer 62 is then etched using a directional process such as reactive ion etching (RIE). As a result of this process, nitride 62 and the thin gate oxide 61 are removed from the bottom of the trench, so that substrate 1 is again exposed; in addition, the edge of the

nitride layer closest to the top of the trench is lowered and given a more rounded shape (see Figure 10). A new gate dielectric 110 is formed at the bottom of the trench, and a blanket layer of polysilicon is deposited which fills the trench (Figure 11). The polysilicon layer 112 is then planarized to again expose the hardmask 17 covering the other gate region and to again expose the HDP oxide 14 surrounding the trench. The polysilicon remaining in the trench is then converted to a silicide 115 (Figure 12).

[0031] While the invention has been described in terms of specific embodiments, it is evident in view of the foregoing description that numerous alternatives, modifications and variations will be apparent to those skilled in the art. Accordingly, the invention is intended to encompass all such alternatives, modifications and variations which fall within the scope and spirit of the invention and the following claims.

[0032] We claim: